

Amendments to the Drawings:

The attached replacement drawing sheet makes changes to Fig. 6 and replaces the original sheet with Fig. 6.

Attachment: Replacement Sheet

REMARKS

Claims 1-5, 7-13 and 15-19 are pending in this application. Claims 7-10 and 15-17 have been withdrawn by the Examiner as a result of a Restriction Requirement. By this Amendment, claims 1 and 2 are amended, claims 18 and 19 are added and claims 6 and 14 are canceled. The features of claims 6 and 14 have been placed into claims 1 and 2, respectively, and claims 1 and 2 have been further amended.

The Office Action did not consider Japanese Patent Publication No. JP-A-4-332404, listed in Applicant's IDS, because no concise explanation of the relevance was provided. U.S. Patent No. 5,302,456 is the equivalent English document for this particular Japanese patent publication. The '456 patent has been cited by Applicant in Information Disclosure Statements filed December 29, 2005 and February 24, 2006 and considered by the Examiner as acknowledged in the 1449 forms returned the Office Action.

An objection was made to Fig. 6 because it was not labeled as "Prior Art". Fig. 6 has been labeled "Prior Art". Withdrawal of the objection is requested.

The claim objection is noted. It is believed that no further action is required by Applicant in that the PTO does not provide a procedure by which Applicant can re-number the claims.

Claims 1-6 and 11-14 have been rejected under 35 U.S.C. §112, first paragraph as being not enabled with respect to the number of compounds one can select for the first, second, and third substances. This rejection is respectfully traversed.

Applicant respectfully disagrees that one of ordinary skill in the art would not be able to choose the right combination of compounds in view of the teachings provided in the specification. Specifically, paragraph [0007] of the specification teaches that the second substance is a compound that "is curable by a reaction with the first substance". Paragraph [0035] teaches use of a pair of liquids: a first liquid contained in microcapsules and a second

liquid in which the microcapsules are dispersed. These two liquids react with each other to cure at normal or low temperatures. This paragraph further teaches as an example that the second liquid is an uncured epoxy resin while the first liquid is any substance or mixture of amines, amidazoles, acid anhydrides, and phenols. In other words, the first and second substances are liquids such as an uncured resin and an appropriate curing agent that would react to form the adhesive. Moreover, paragraph [0036] of the specification teaches "the materials for the first and second liquids may be exchanged." Claim sets 3, 4 and 11, 12 are directed to examples of these alternate embodiments and provide examples of specific compounds that could work for the first and second compounds. Once it is determined whether the first substance is to be the curing agent or the curable compound, the second substance logically has to be the other compound. As such, one of ordinary skill in the art would understand that the combination of compounds is limited.

Similarly, paragraphs [0010], [0011] and [0043] teach that the third substance is a compound that reacts with the second substance to cure the adhesive during heating. Examples of compounds that are suitable for the third substance when the second substance is an epoxy resin are provided in paragraph [0043]. A person skilled in the art would be able to determine which compounds are appropriate to use as the first, second, and third substances given the logical recitations of the claims (i.e., the first and second compounds react with each other once the microcapsules are crushed; the second and third substances react with each other under heating). In view of the above, applicant respectfully submits that the claims are enabled.

The claims were rejected under 35 U.S.C. §102(b) on two bases. First, claims 1-4, 6, 11, 12 and 14 are rejected over Date (U.S. Patent Publication No. 2002/0084019). In addition, claims 1-3, 5-11, 13 and 14 are rejected over Matsui (U.S. Patent No. 5,302,456). The currently amended claims overcome both of these rejections because neither of these

references teaches a third substance that is dispersed in the second substance prior to curing to react with the second substance under heating to form the adhesive.

With respect to the rejection based on Date, its adhesives are characterized as "two pack" (for example see paragraph [0020]) comprised of an A agent and a B agent. The A agent is selected from components including an acrylic monomer, a peroxide, a reducing agent, an epoxy resin precursor, and a curing agent where at least one or two of the acrylic monomer, a peroxide, a reducing agent are included in Agent A. Agent B includes all of the remaining components not selected for Agent A. In the Examples provided in Date where the epoxy resin precursor is provided in Agent A and its curing agent in Agent B, this reference fails to teach a third substance that is curable by a reaction with the second substance, the reaction occurring by heating, to form the adhesive.

Matsui teaches substances that are heat curable with epoxy resin and that are contained within microcapsules. The microcapsules further contain the conductive particles. Therefore, Matsui does not teach or suggest the adhesive described in claim 2 and its associated dependent claims 11-13 and 19. With respect to claim 1 and its dependent claims 3-5 and 18, Matsui teaches that "only the electrical pads of the LSI chip and the electrode terminals of the wiring substrate become connectable to each other, the other portions of the LSI chip and the wiring substrate are maintained in an insulated condition because of the insulative resin of the surface of the micro-capsules." (See column 3, lines 8-13.) As such, this reference fails to teach or suggest a third substance curable by reaction with the second substance, the reaction occurring by heating, because there is no heating of the Matsui substances (which in order to correspond to the claims must be considered as the second and third substances) in the "other portions" of this reference's adhesive.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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JAO:LES/ccs

Attachment:
Replacement Sheet (1)

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